2SD2565

Silicon NPN triple diffusion planar type

For high voltage-withstand switching

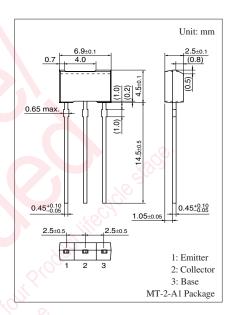
■ Features

- ullet High collector-base voltage (Emitter open) V_{CBO}
- High collector-emitter voltage (Base open) V_{CEO}
- Large collector power dissipation P_C
- Low collector-emitter saturation voltage V_{CE(sat)}
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	400	V	
Collector-emitter voltage (Base open)	V _{CEO}	400	V	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_{C}	0.5	A	
Peak collector current	I _{CP}	1	A	
Collector power dissipation *	P _C	1	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	S°C	

Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

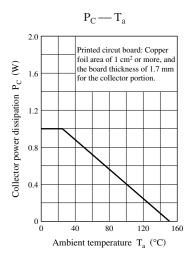


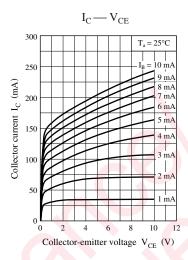
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

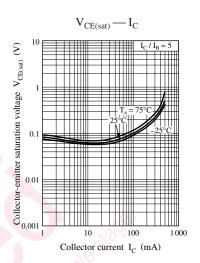
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 100 \mu A, I_E = 0$	400			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 500 \ \mu A, I_B = 0$	400			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 100 \ \mu A, I_C = 0$	5			V
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 30 \text{ mA}$	30			_
Collector-emitter saturation voltage *	V _{CE(sat)}	$I_C = 250 \text{ mA}, I_B = 50 \text{ mA}$			1.5	V
Base-emitter saturation voltage *	V _{BE(sat)}	$I_C = 250 \text{ mA}, I_B = 50 \text{ mA}$			1.5	V
Transition frequency	f_T	$V_{CB} = 30 \text{ V}, I_E = -20 \text{ mA}, f = 200 \text{ MHz}$		30		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 30 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		6	20	pF
Turn-on time	t _{on}	$I_C = 100 \text{ mA}$		0.8		μs
Storage time	t _{stg}	$I_{B1} = 10 \text{ mA}, I_{B2} = -10 \text{ mA}$		3.7		μs
Fall time	t _f	$V_{CC} = 200 \text{ V}$		0.6		μs

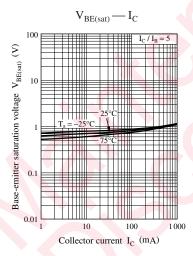
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

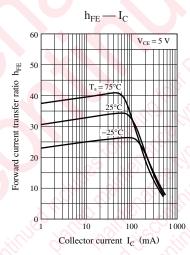
2. *: Pulse measurement

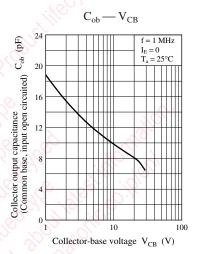












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